



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. PicoStar™ package configuration.
  - $\triangle D$  The package size (Dimension D and E) of a particular device is specified in the device Product Data Sheet version of this drawing, in case it cannot be found in the product data sheet please contact a local TI representative.
  - $\triangle E$  Reference Product Data Sheet for array population. 2 x 4 matrix pattern is shown for illustration only.
  - F. This package is a Pb-free solder land design.

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